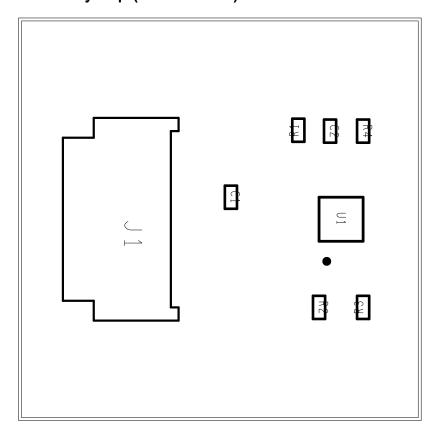
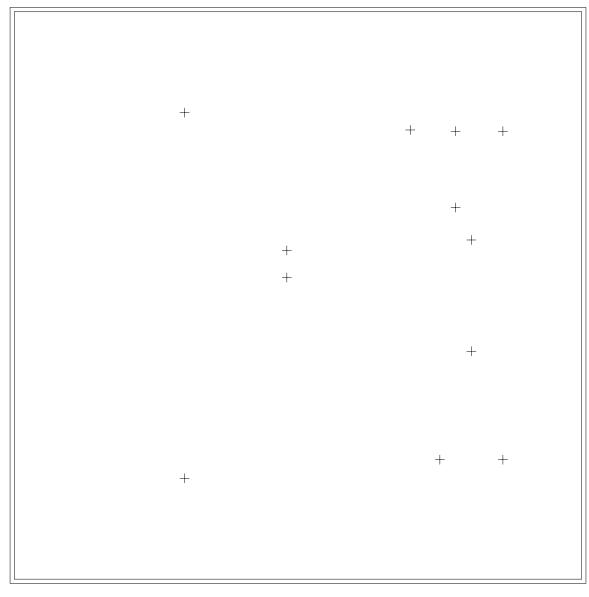
## Assembly Top (Scale 5.83:1)



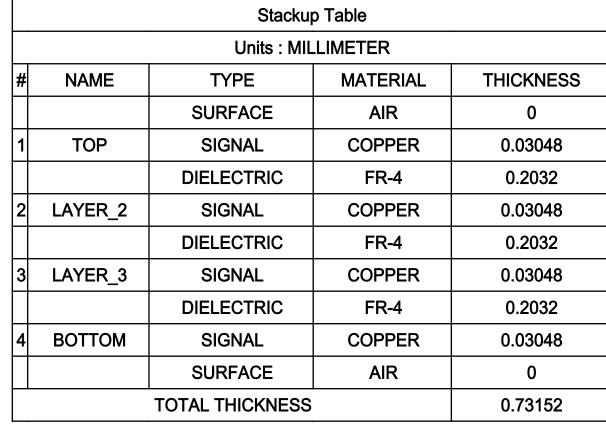
## **FAB NOTES**

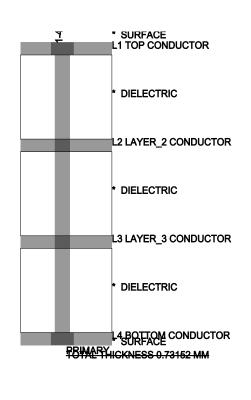
- 1. LATEST VERSION OF ALL REFERENCED SPECIFICATIONS TO BE USED UNLESS OTHERWISE SPECIFIED.
- 2. FABRICATE IN ACCORDANCE WITH IPC-6012 CLASS 2 UNLESS OTHERWISE SPECIFIED.
- 3. INSPECT IN ACCORDANCE WITH IPC-A-600 CLASS 2 UNLESS OTHERWISE SPECIFIED.
- 4. MATERIAL: BASE LAMINATE, COPPER CLAD, GLASS-BASED EPOXY RESIN, FLAME RETARDENT, IN ACCORDANCE WITH MIL-P-13949, TYPE GF. THICKNESS SEE STACKUP. FINISHED BOARD MUST MEET UL94V-0. MUST CONFORM TO IPC-410A/24/26/29/98/126, Tg>175 deg C, Td>330 deg C, T260>30 MIN, T288>5 MIN, CTEz (50-260 deg C)<3.5% (6 PASSES). MATERIAL MUST BE RoHS COMPLIANT
- 5. FINAL CONDUCTOR SURFACE FINISH TO BE 3-10 MICRO-INCHES OF IMMERSION GOLD OVER 100-250 MICRO-INCHES OF ELECTROLESS NICKEL PER IPC-4552.
- 6. PLATED-THRU HOLES TO HAVE COPPER WALL THICKNESS NOT LESS THAN 0.001" THICKNESS TO BE DETERMINED BY IPC-6012, CLASS 2.
- 7. SILKSCREEN TO BE WHITE PERMANENT NON-CONDUCTIVE (LEGIBLE) INK AND NOT TO COVER ANY PORTION OF A PAD NOT COVERED BY SOLDERMASK. FABRICATOR TO CLIP ANY NON-CONFORMING SILKSCREEN NOMENCLATURE.
- 8. UL LOGO AND DATE-CODE & VENDOR-CODE MUST APPEAR IN ETCH ON PRIMARY SIDE. SECONDARY SIDE IS ACCEPTABLE IF THERE IS NO ROOM ON PRIMARY SIDE.
- 9. USE LPI SOLDER MASK OVER BARE COPPER PER SUPPLIED ARTWORK PER IPC-SM-840C, CLASS T. MUST BE RoHS COMPLIANT. COLOR MATTE-GREEN. MASK GERBER FILES ARE SET TO 1:1 WITH OUTER LAYERS. FABRICATOR TO SET AS REQUIRED.
- 10. SOLDER MASK SHALL BE CAPABLE OF FIVE SOLDER EXPOSURES AT 500 deg F.
- 11. TOOLING HOLES MUST BE PRIMARY DRILLED AT THE SAME TIME AS PLATED-THRU HOLES. ALL HOLES MUST BE WITHIN 0.003" OF RADIAL TRUE POSITION.
- 12. DIMENSIONAL TOLERANCES ON PCB ARE AS FOLLOWS UNLESS OTHERWISE SPECIFIED: HOLE TO HOLE +/- 0.005"
  HOLE TO EDGE +/- 0.010"
  EDGE TO EDGE +/- 0.010"
- 13. PADS MUST BE FINISHED TO WITHIN +/- 0.0015" OF MINOR DIMENSION (PAD WIDTH) & +/- 0.002" OF THE MAJOR DIMENSION (PAD LENGTH).
- 14. GLOBAL AND LOCAL FIDUCIALS MUST BE FREE OF ANY MARKINGS
- 15. REMOVAL OF NON-FUNCTIONAL PADS ON INNER LAYERS ALLOWED.
- 16. COPPER THEIVING OF ANY LAYERS IS NOT ACCEPTABLE UNLESS OTHERWISE SPECIFIED BY DESIGN.
- 17. FULL NETLIST TESTING REQUIRED UNLESS OTHERWISE SPECIFIED. TESTING SHOULD CONFORM TO IPC-ET-652.
- 18. PRIOR TO BOARD FABRICATION, COMPARE GERBER DATA TO SUPPLIED IPC-D-356A NETLIST. REPORT ALL DISCREPANCIES.
- 19. FINISHED PRODUCT TO BE RoHS COMPLIANT AND MEET EU RoHS DIRECTIVE 2015/863/EU.
- 20. CENTERLINES ARE THE EDGE OF INTERNAL SLOTS/CUTOUTS (IF ANY)
- 21. USE GERBER FILE "ASSYTP.ART" FOR BOARD OUTLINE DIMENSIONS AND SHAPE.

Drill drawing 1-4 (Scale 8.34:1)



DRILL CHART 1-4									
ALL UNITS ARE IN MILLIMETERS (MILS)									
FIGURE	FINISHED_SIZE	TOLERANCE_DRILL	PLATED	QTY					
	0.305 (12.000)	+0.076/-0.305	PLATED	12					





UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN ? TOLERANCE ON ANGLE +/- ? 2PL +/- ? 3PL +/- ? INTERPRET DIM AND TOL		
PER ASME Y14.5 - ? THIRD ANGLE PROJECTION	Document Number	
THIRD ANGLE PROJECTION	Title FPC Temperature Sensor	
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Assembly Top (Scale 1:1)				
Assembly Bottom (Scale 1:1)				
			UN DIN TO 2P 3P IN PE	LESS OTHERWISE SPECIFIED  MENSIONS ARE IN ?  LERANCE ON ANGLE +/- ?  L +/- ?  L +/- ?  TERPRET DIM AND TOL  R ASME Y14.5 - ?  THIRD ANGLE PROJECTION

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 Thu, 26 Jun 2025 01:26:14 GMT
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